

ABSTRACT

A non-leaded semiconductor device which does not cause a flaw and contamination with a foreign substance on mounting surfaces of external electrode terminals of another non-leaded semiconductor device, and a method of fabricating the same. In fabrication of the non-leaded semiconductor device, a matrix-type leadframe containing a matrix of a plurality of unit leadframe patterns is prepared, a semiconductor chip is secured on each unit leadframe pattern, conductive wires are connected between electrodes of the semiconductor chip and inner ends of terminal leads of each unit leadframe pattern, and then single-sided molding is performed to encapsulate the semiconductor chip, conductive wires, and inner end parts of terminal leads in a package part. In this single-sided molding, a contact-preventive part thicker than the package part is formed outside the package part using injected resin. A plurality of the matrix-type leadframes thus processed are stacked one on top of another when the leadframes are stored or supplied. In a stack of the matrix-type leadframes, surfaces of terminal leads serving as external electrode terminals are not flawed or contaminated since the contact-preventive part is located between the leadframes at upper and lower stack positions. Then, each unit leadframe pattern is cut to provide a non-leaded semiconductor device.